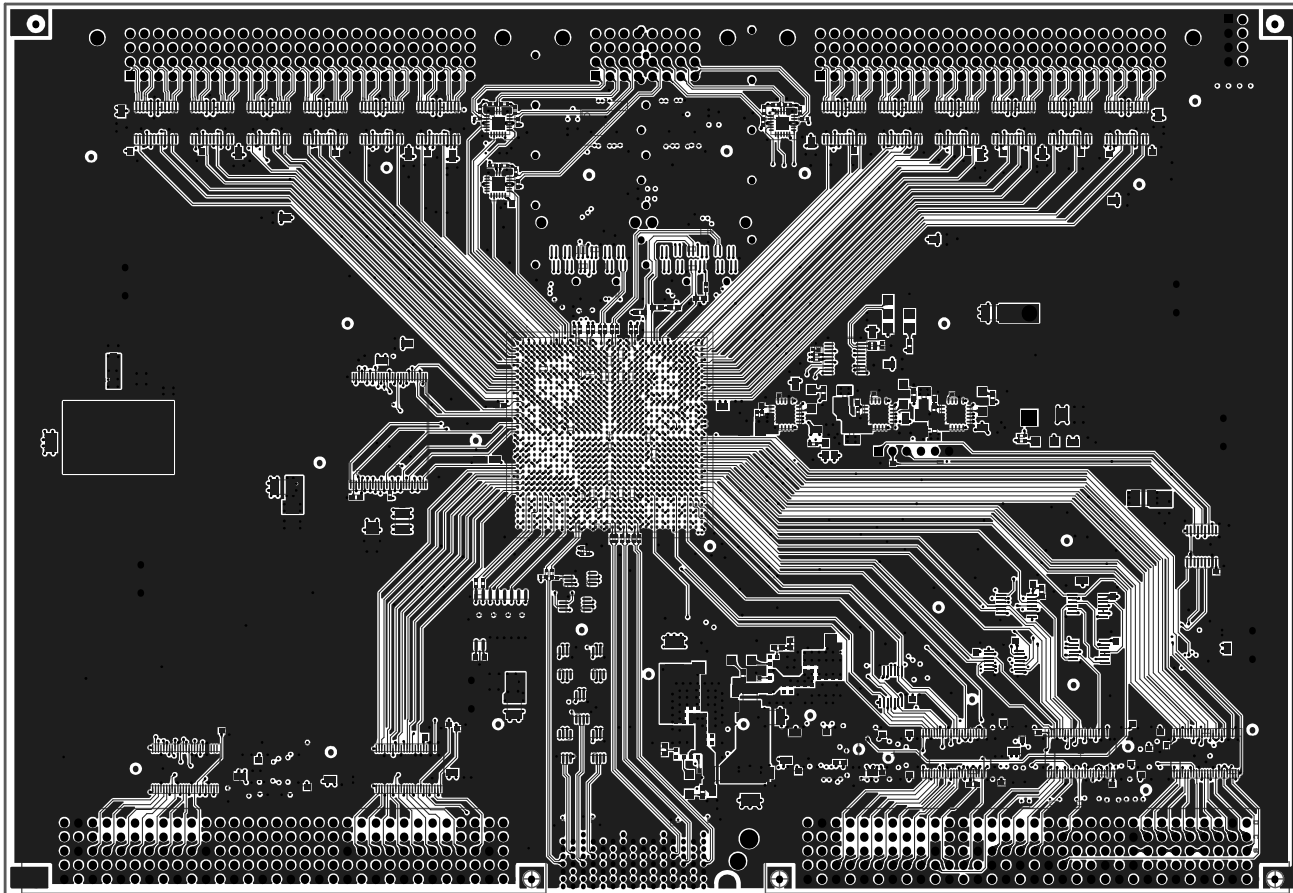
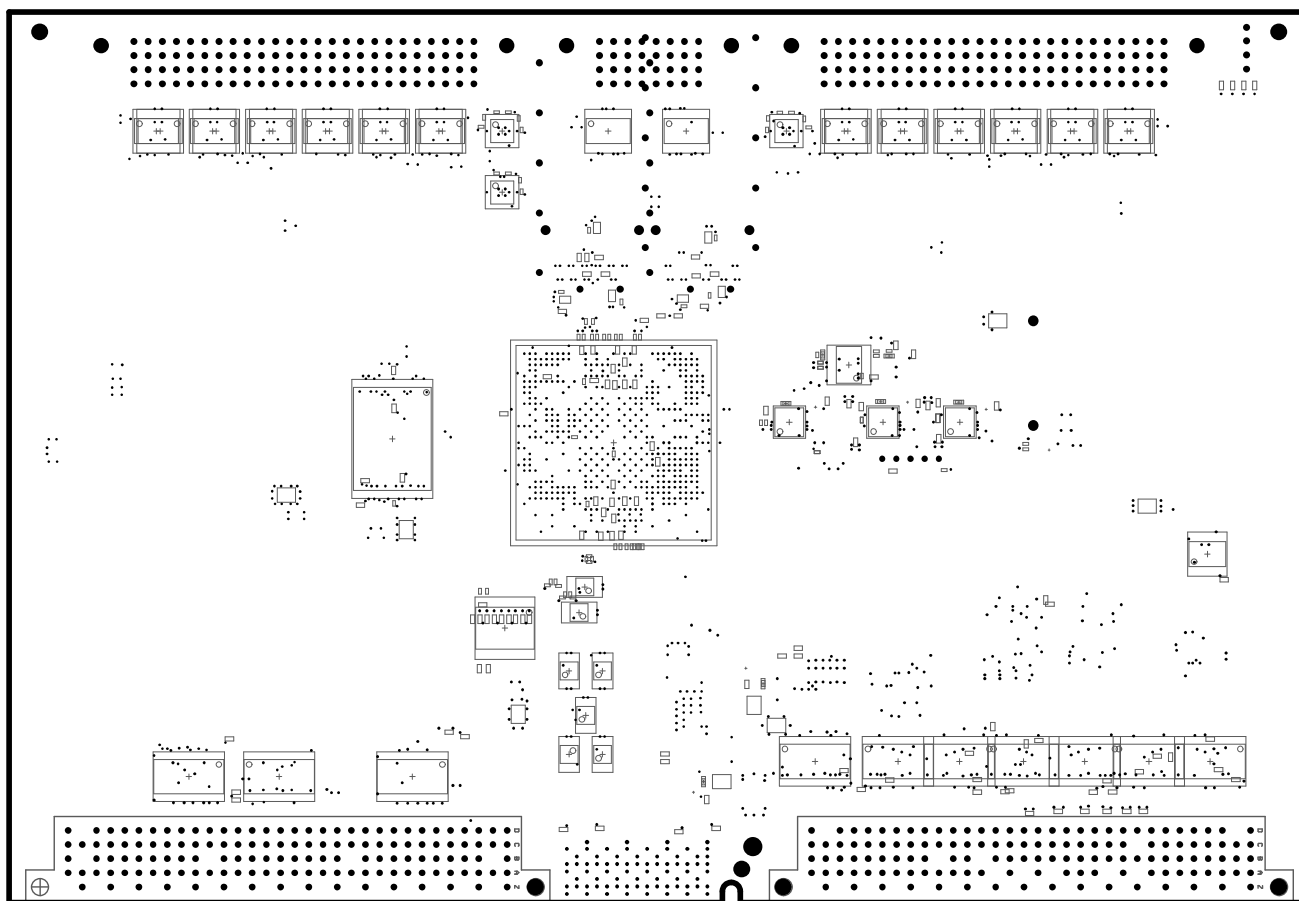


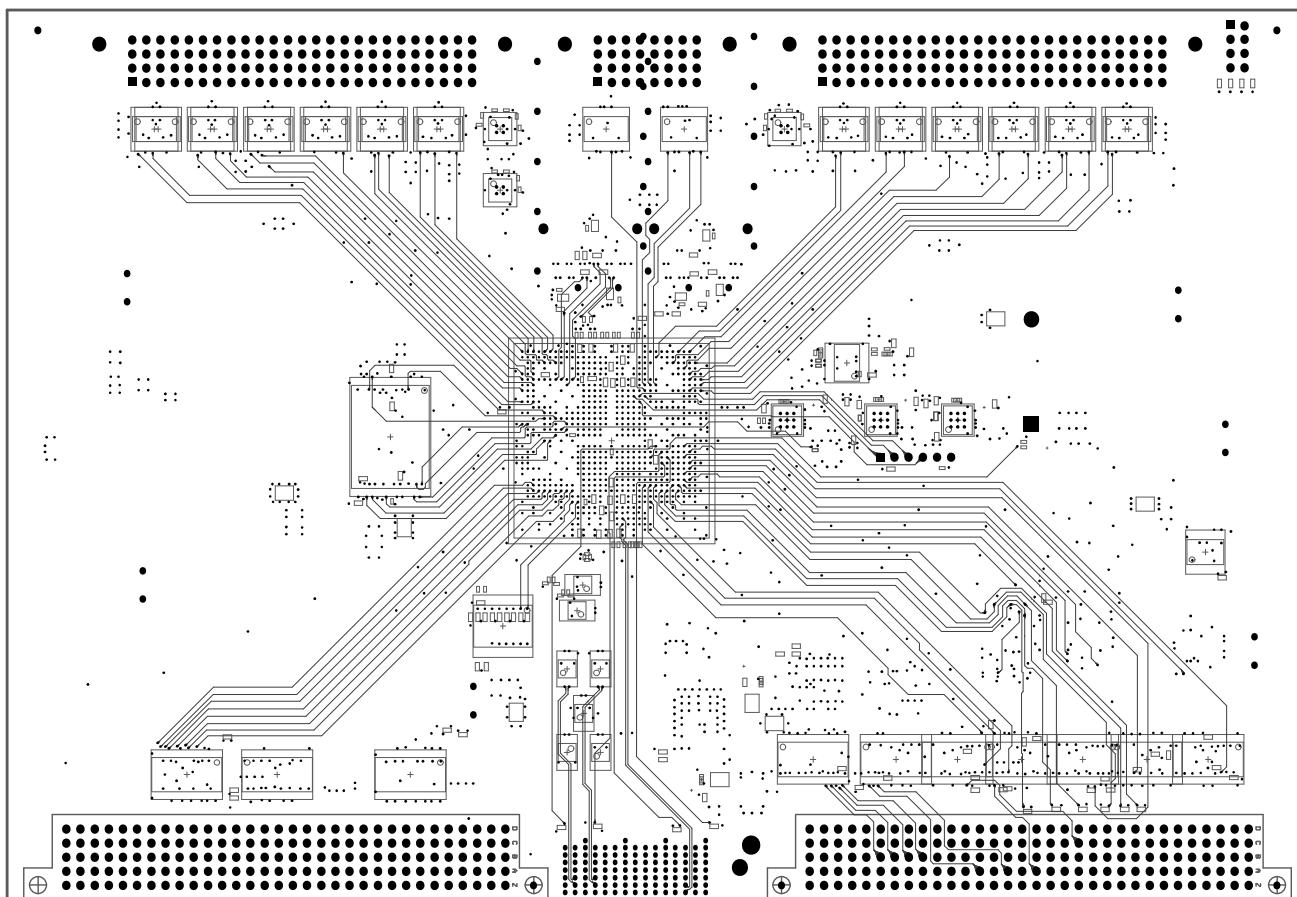
UETROC.PcbDoc
TopLayer

.GTL

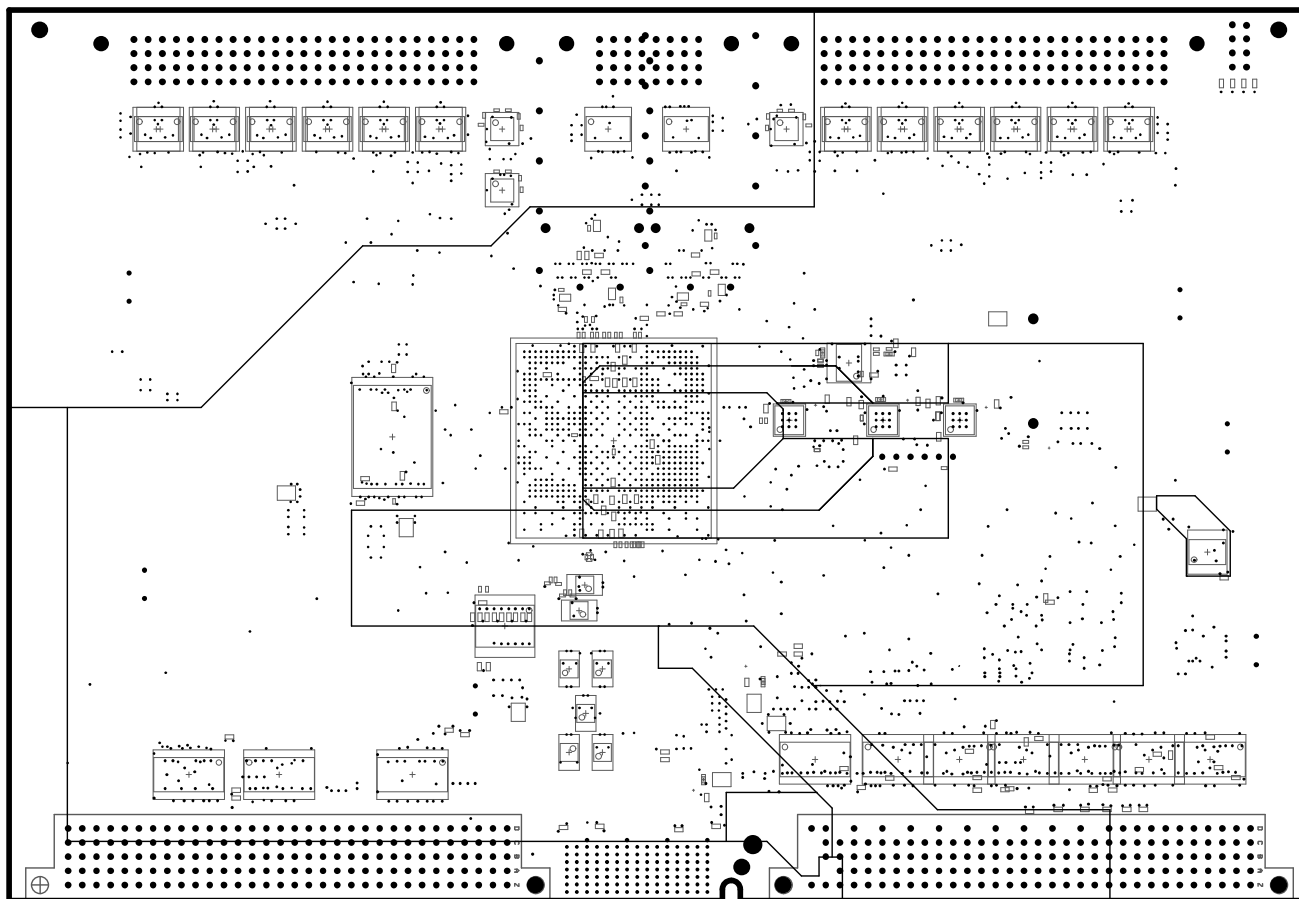


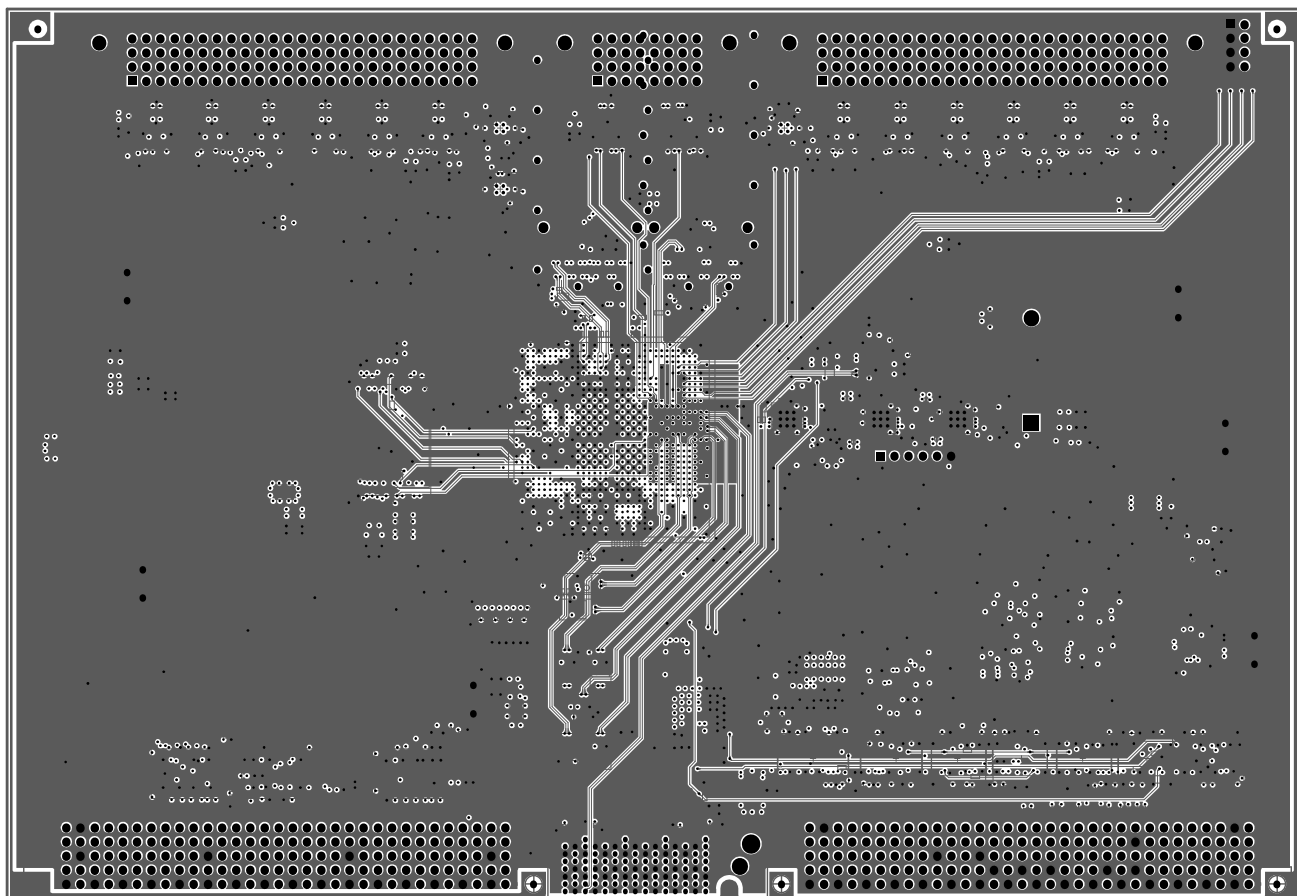
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GroundPlane (GND) .GP1

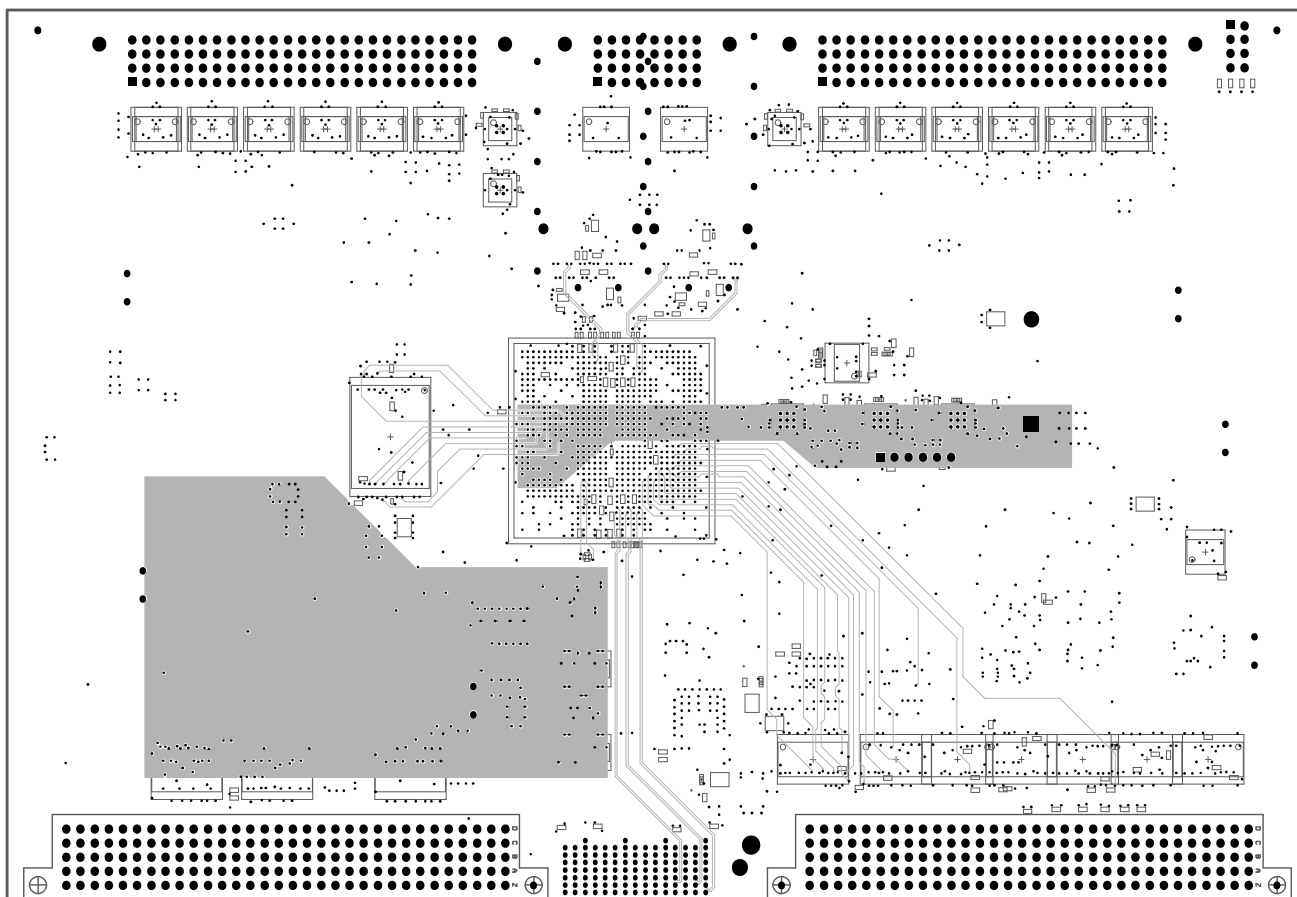




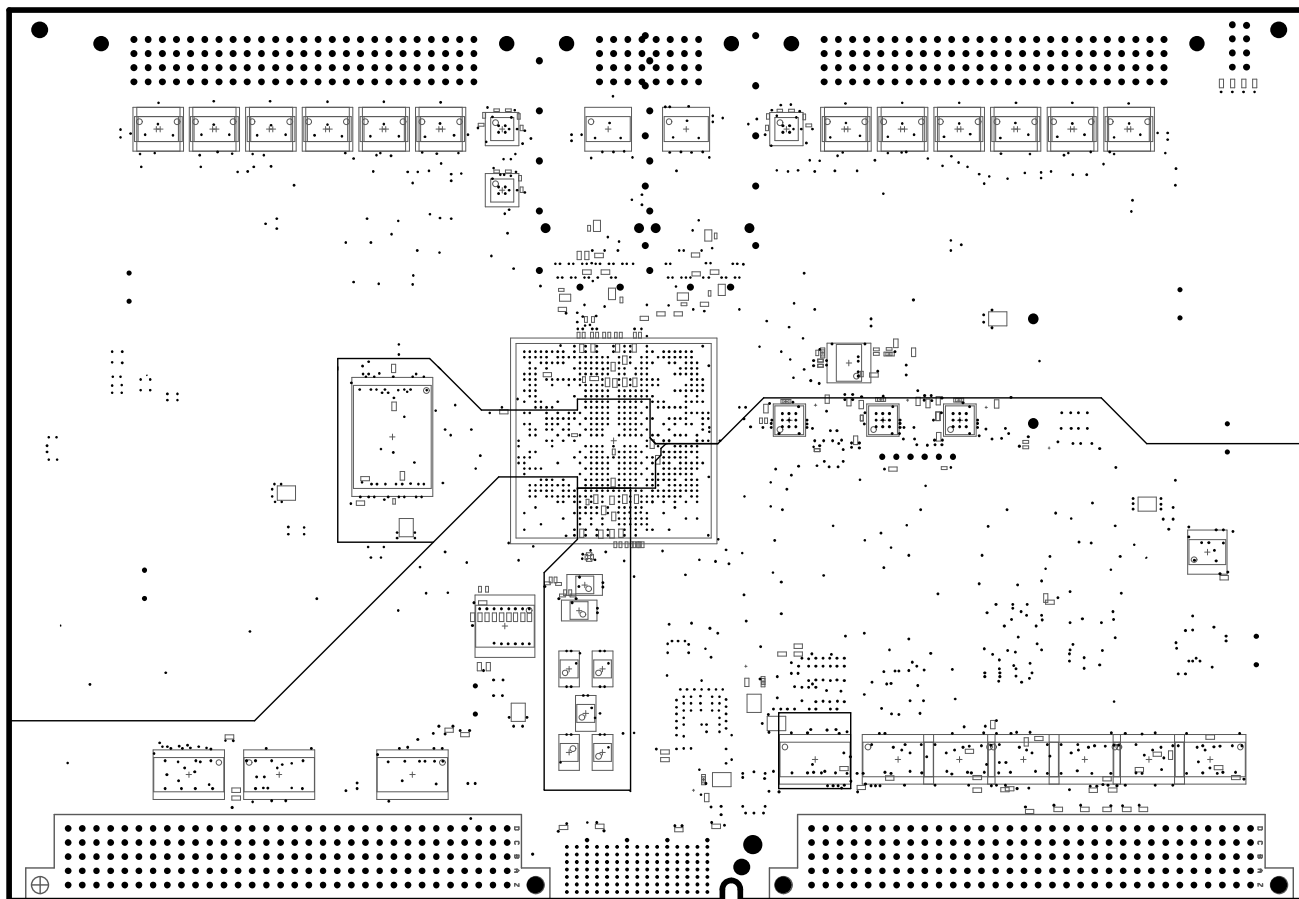
UETROC.PcbDoc
PowerPlane <<Multiple NGR>>

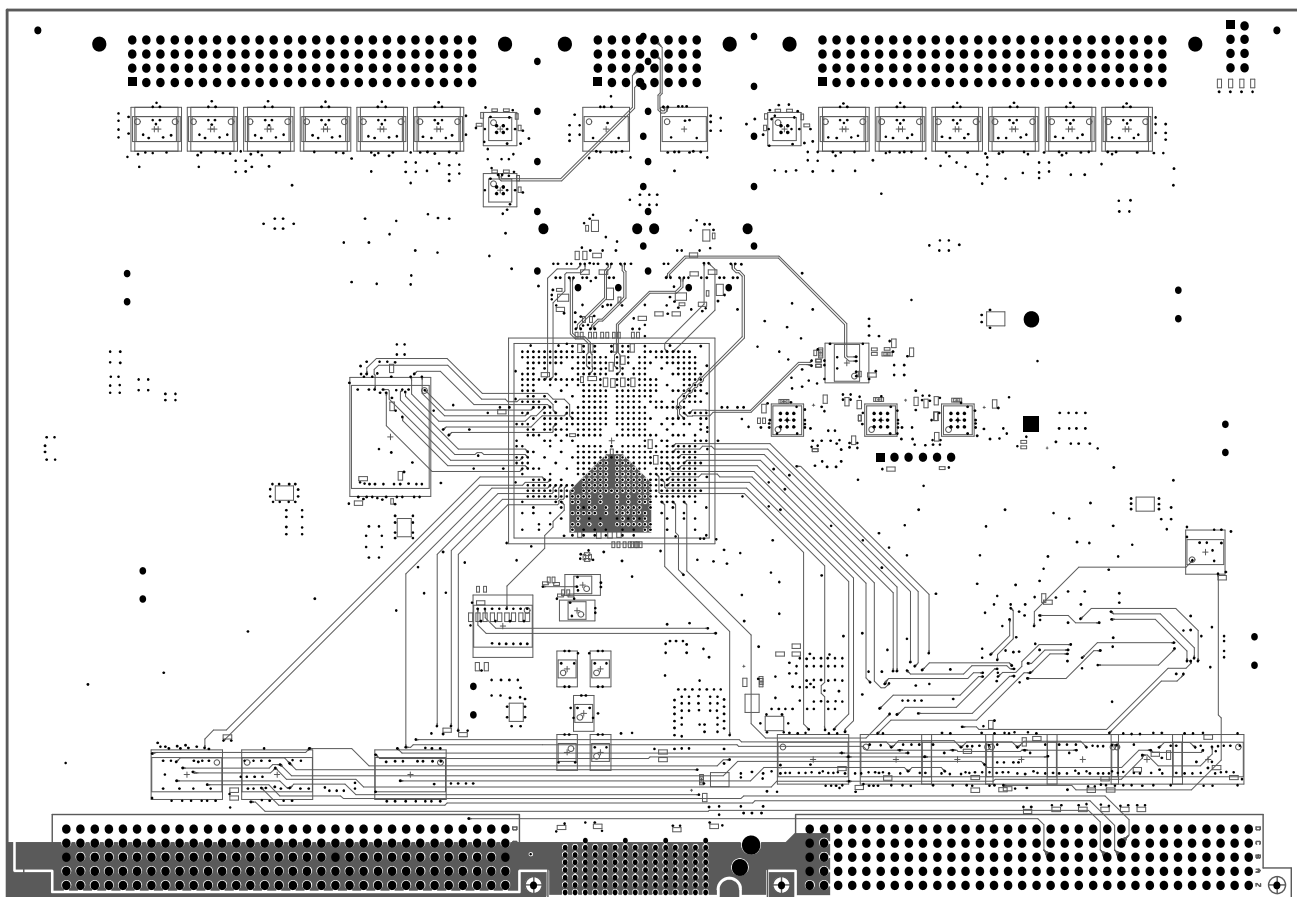


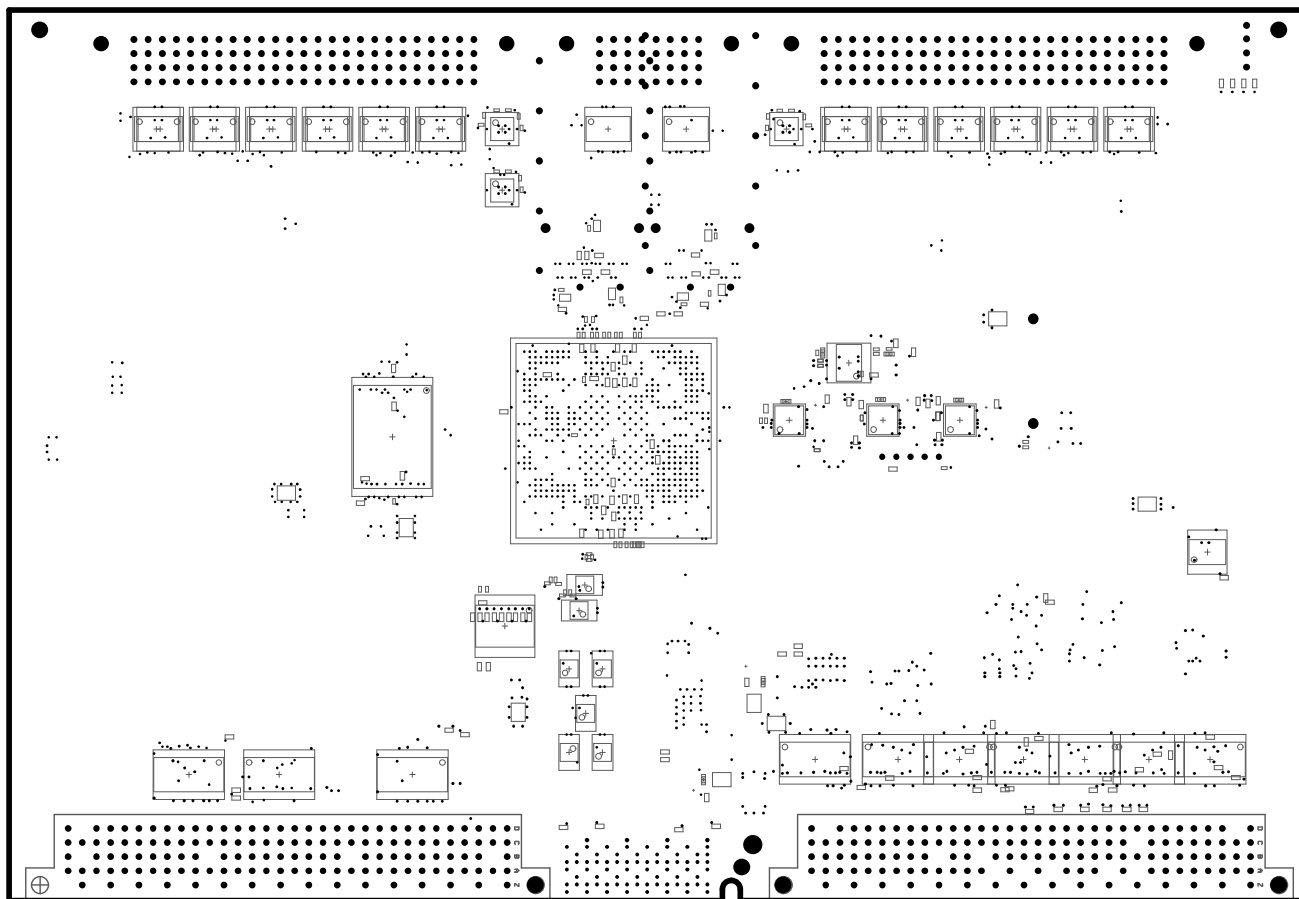




UETROC.PcbDoc
PowerPlane2 <<Multiple GPls>>

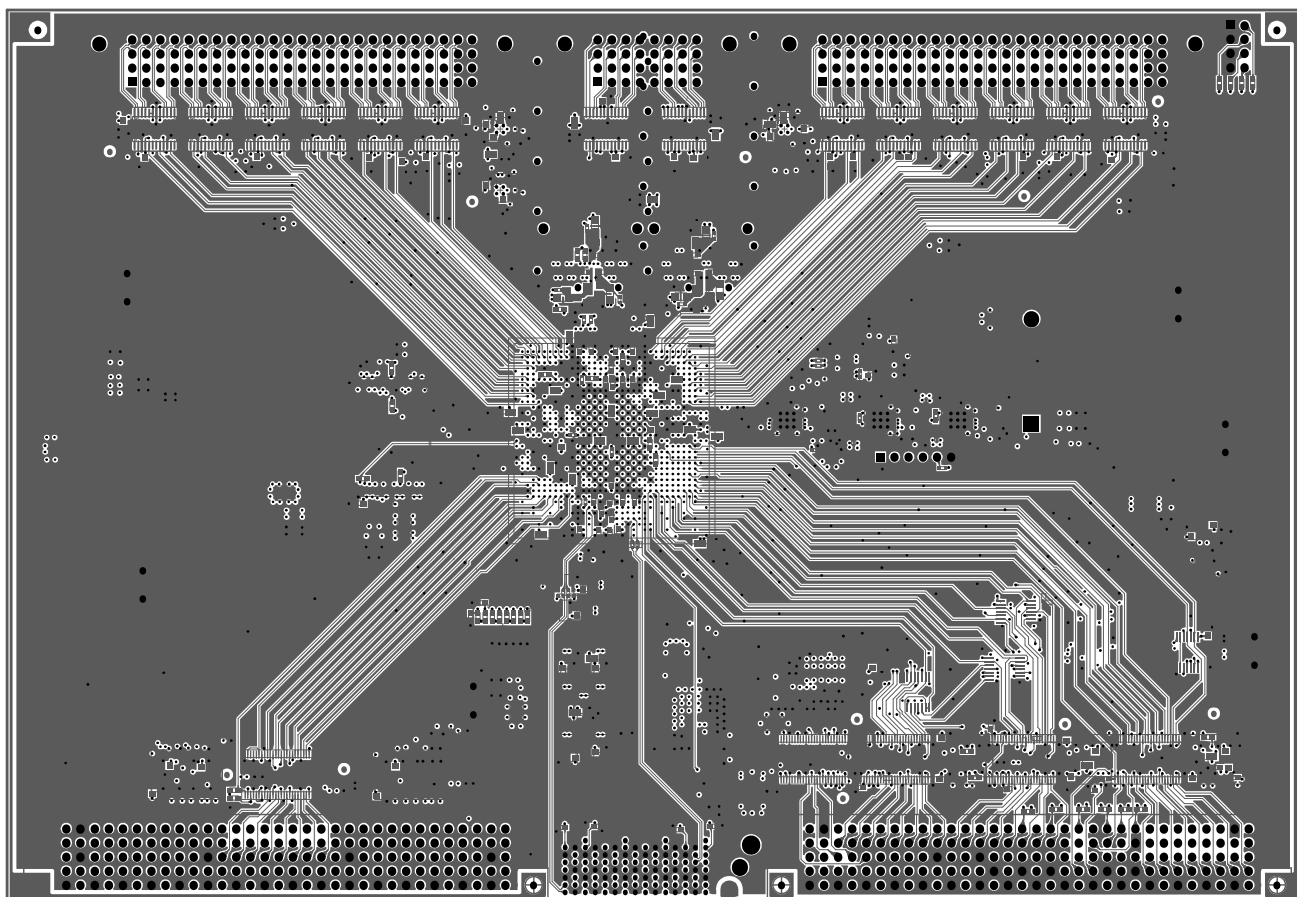




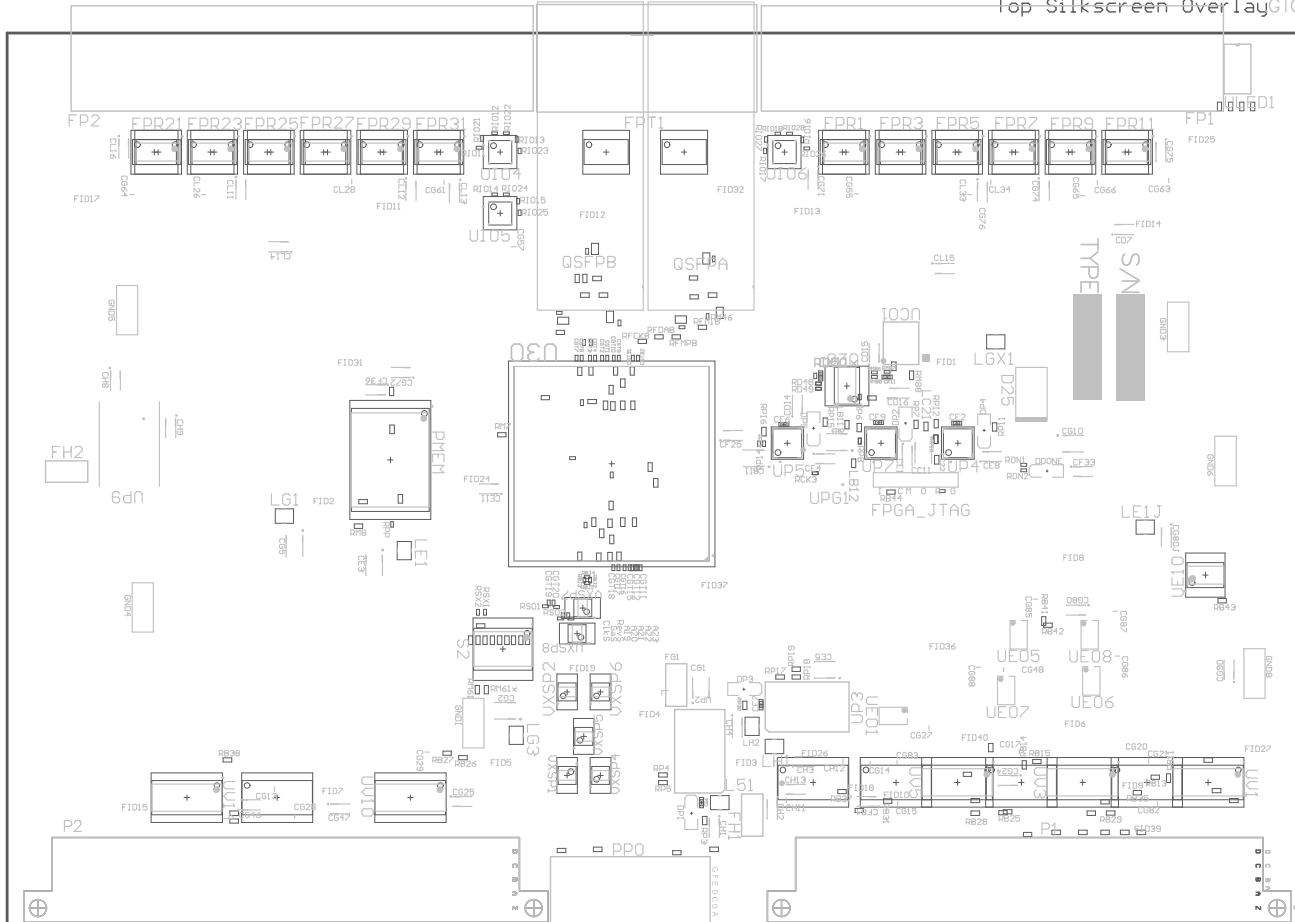


UETROC.PcbDoc
BottomLayer

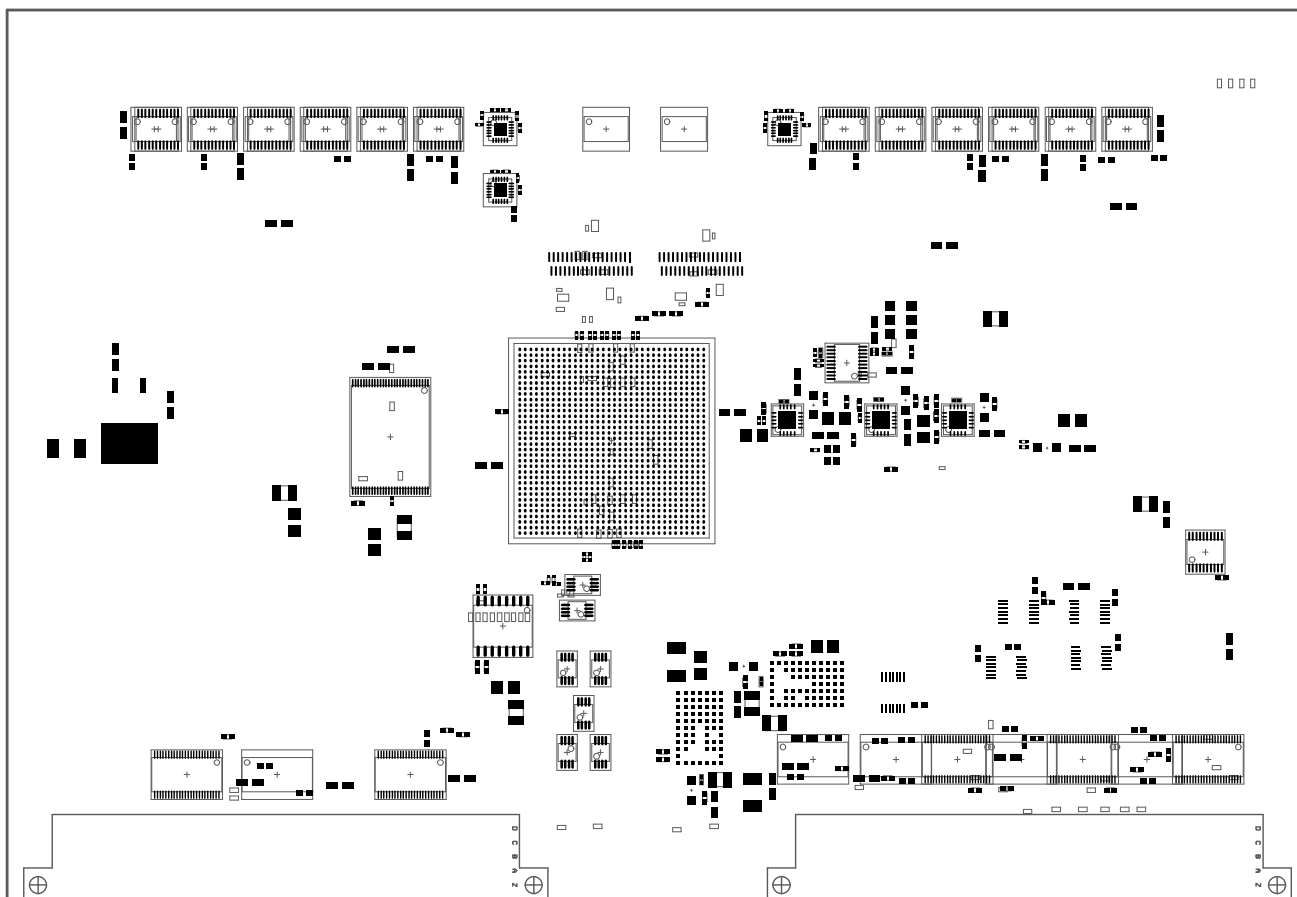
.GBL



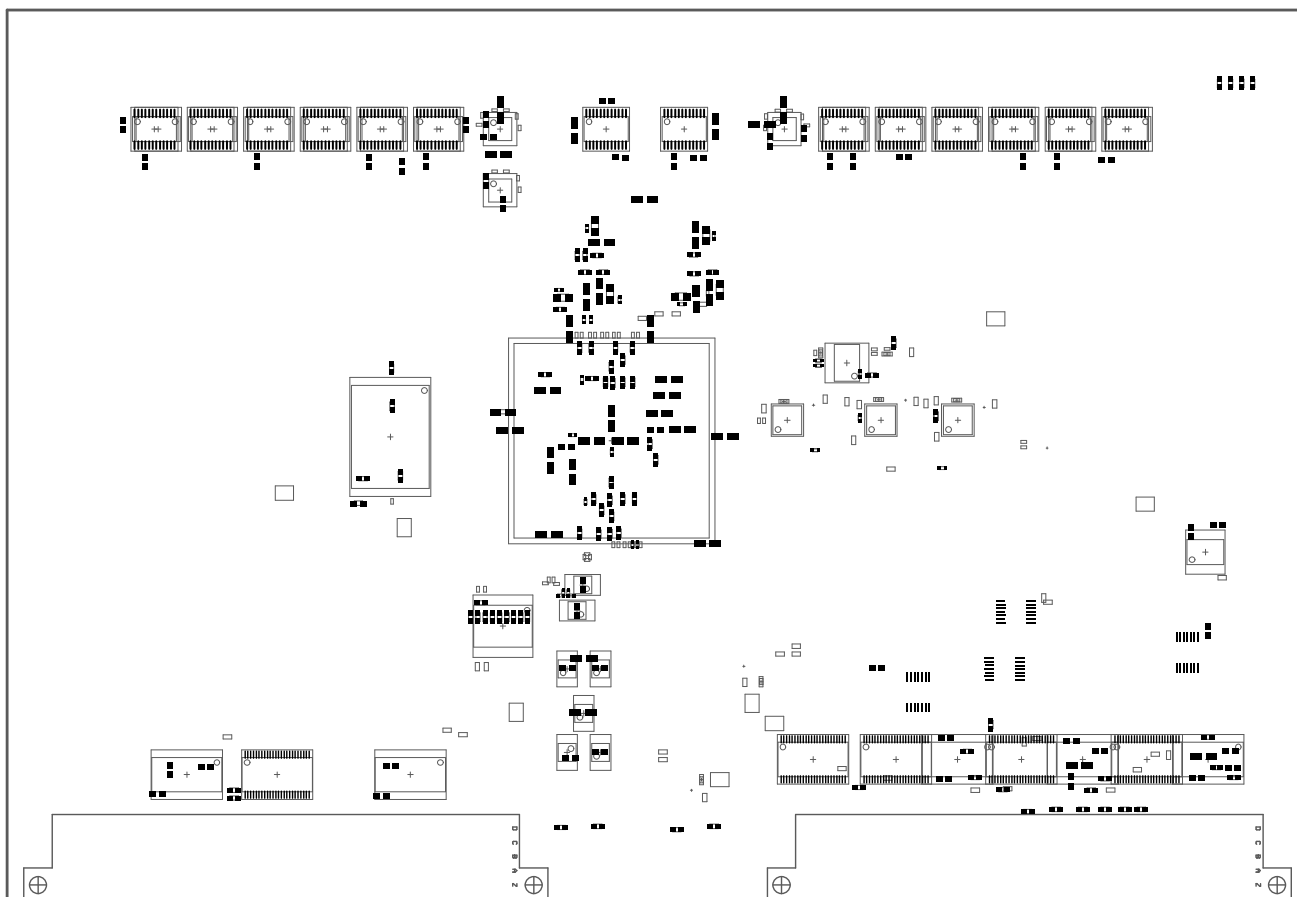
UETROC.PcbDoc
Top Silkscreen OverlayGTO



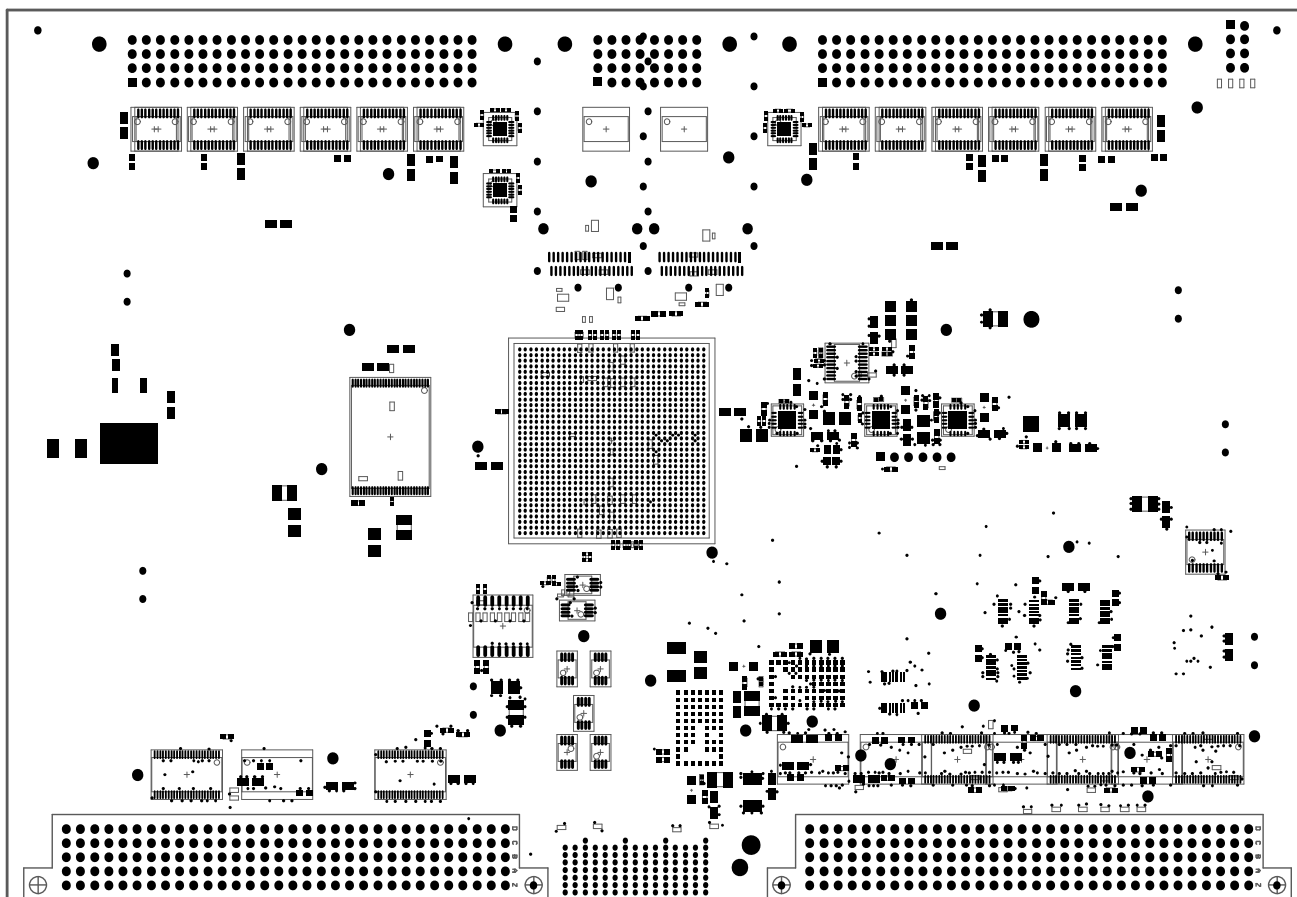
UETROC.PcbDoc
Top Paste Mask Print .GTP



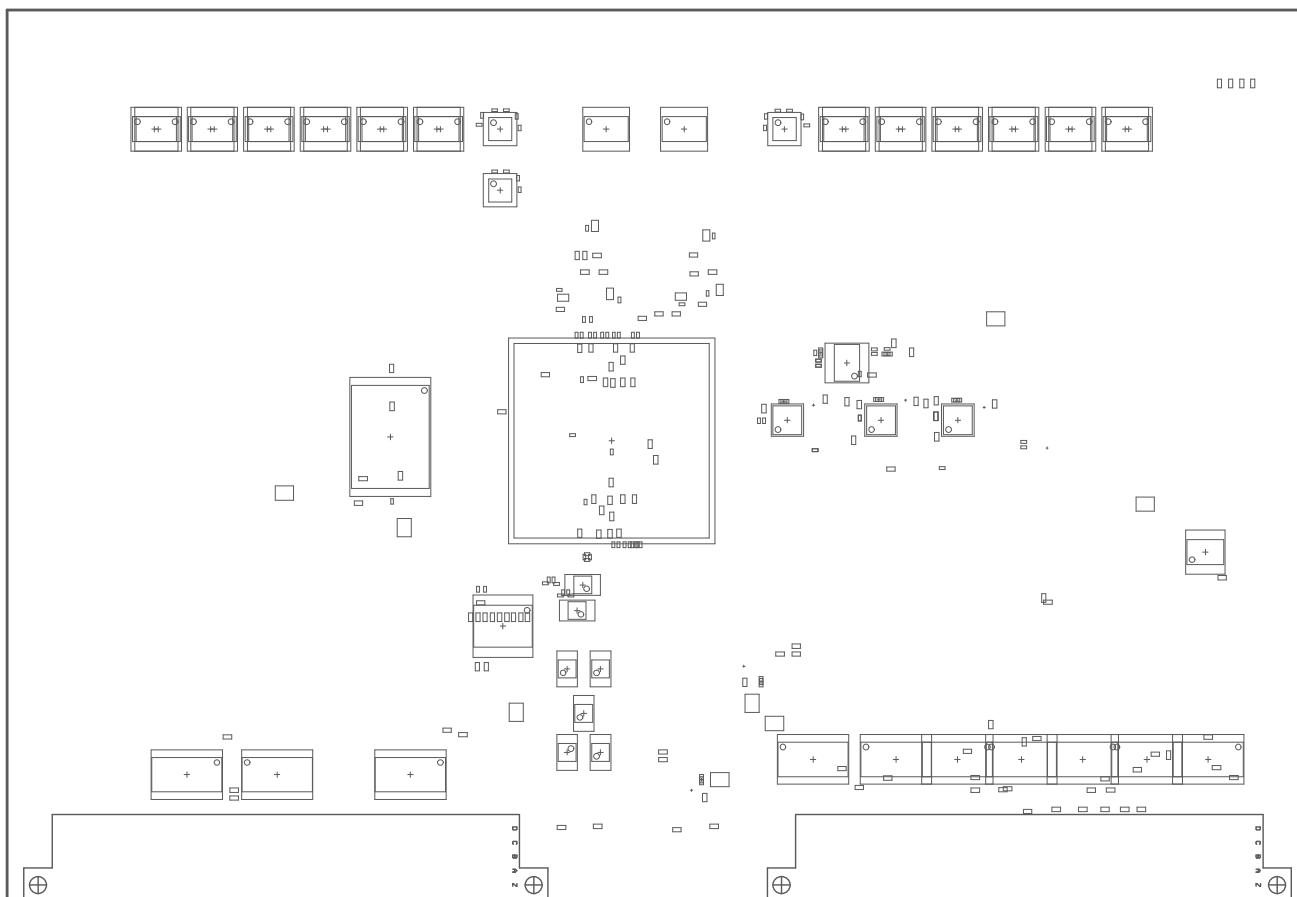
UETROC.PcbDoc
Bottom Paste Mask PrinGBP



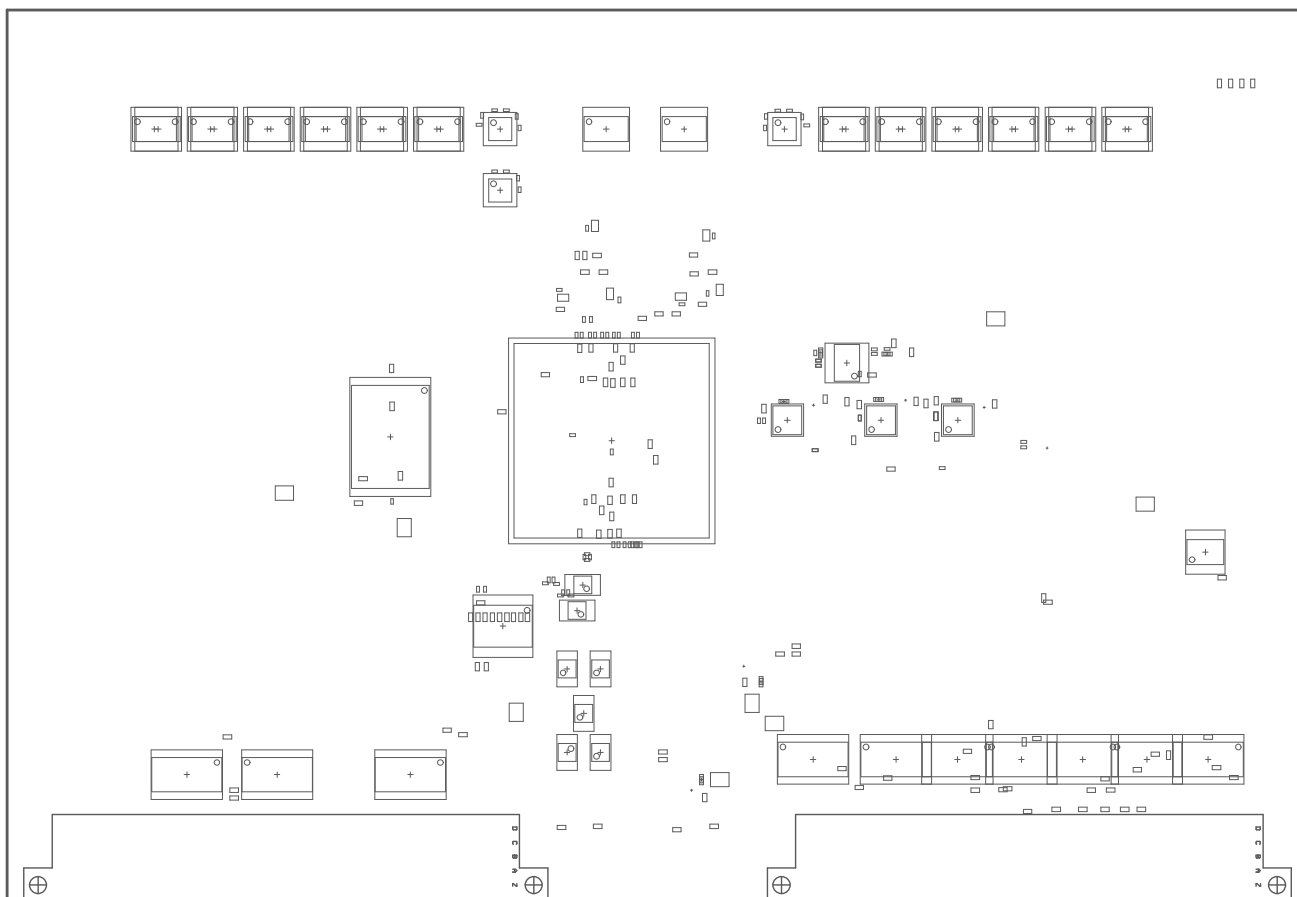
UETROC.PcbDoc
Top Solder Mask Print .GTS

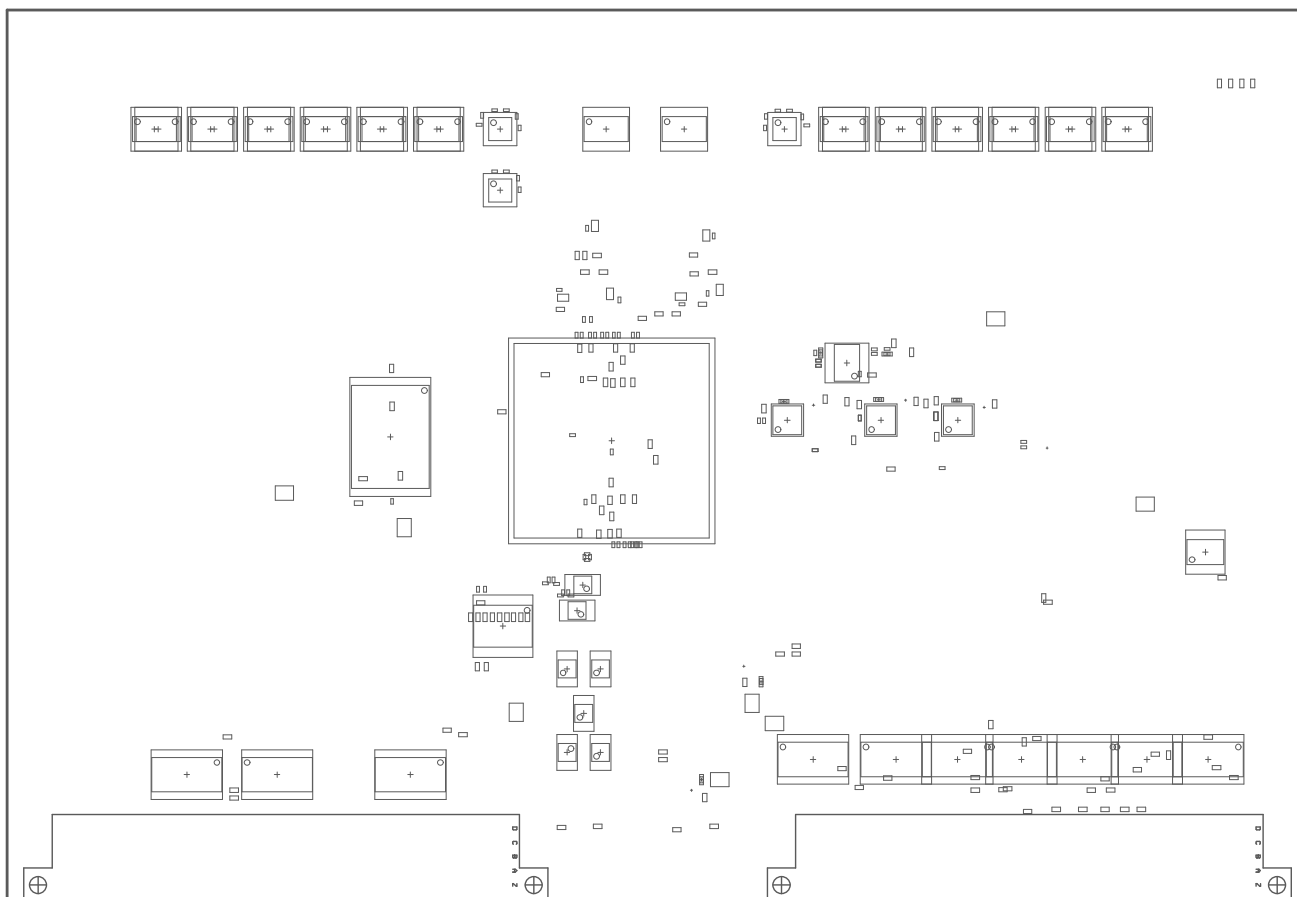


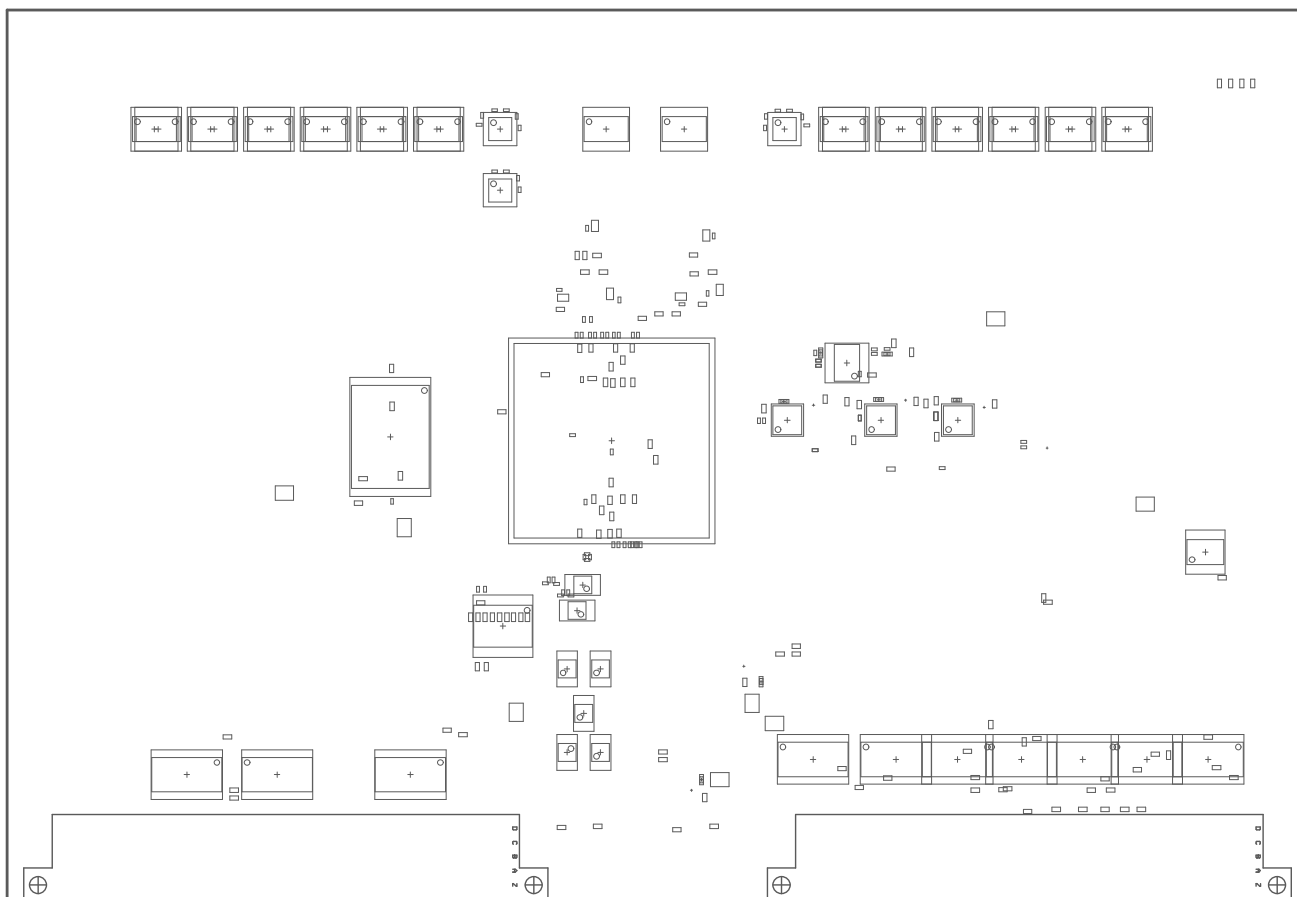
UETROC.PcbDoc
Mechanical1



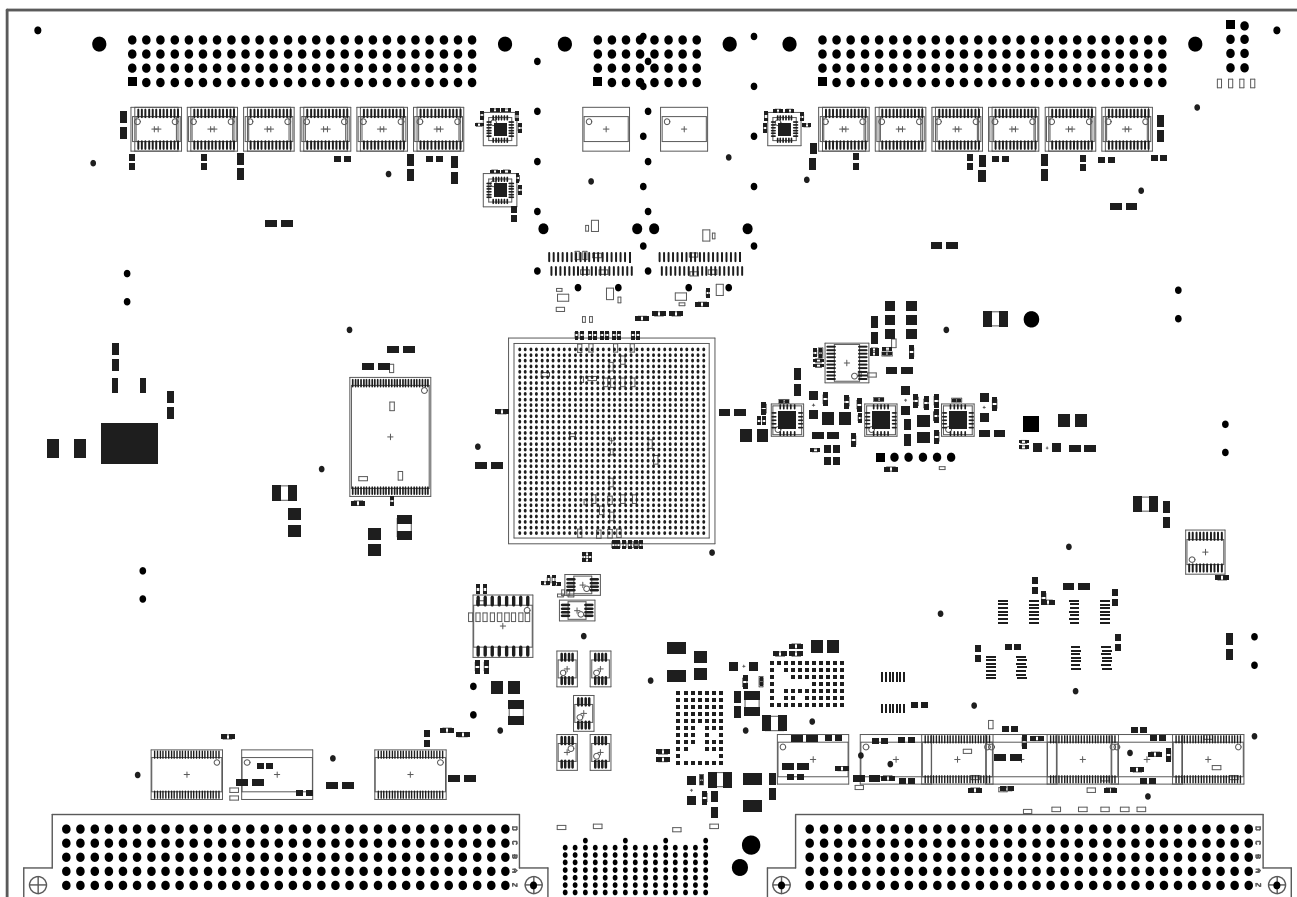
UETROC.PcbDoc
Mechanical4



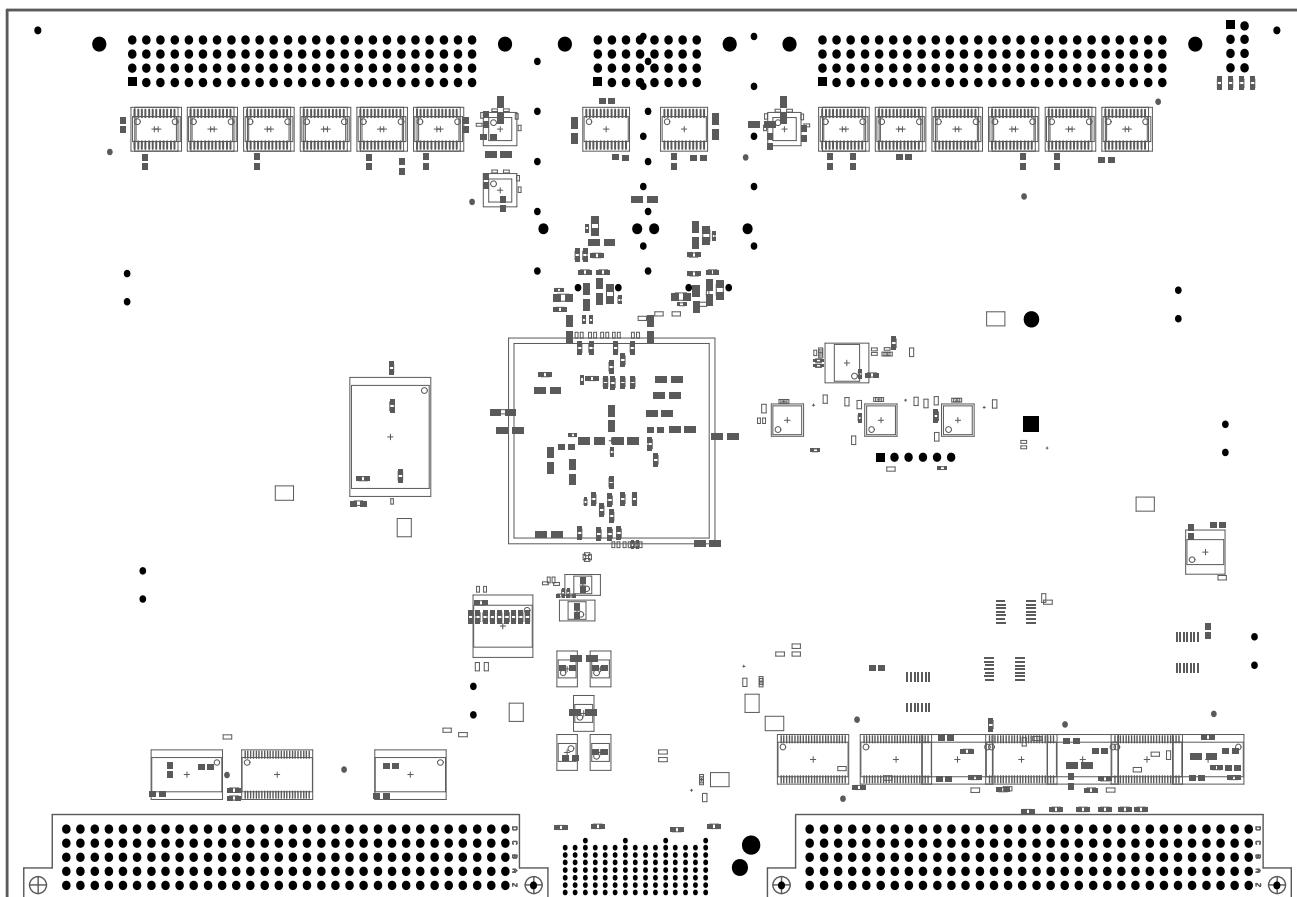




UETROC.PcbDoc
Top Pad Master

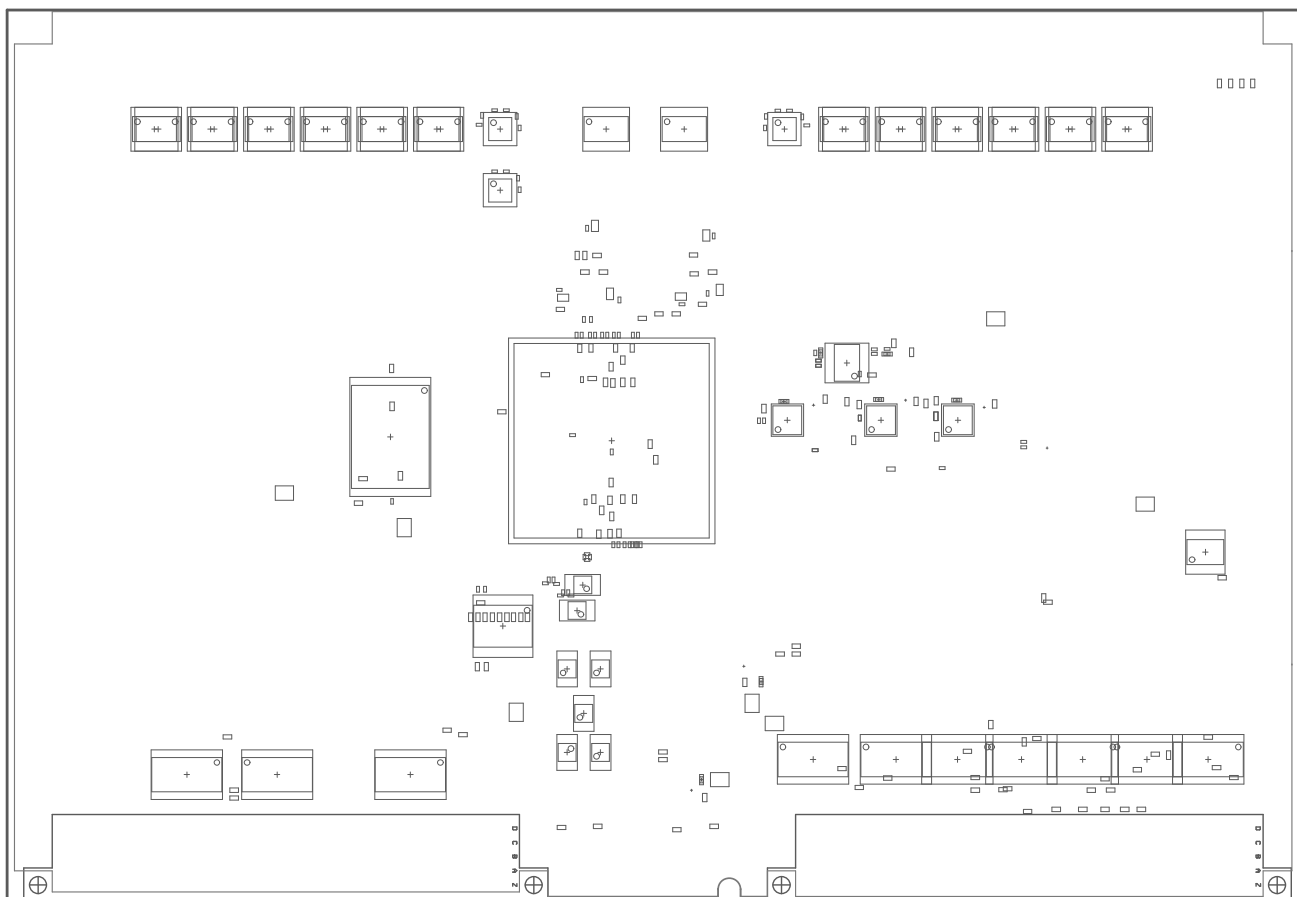


UETROC.PcbDoc
Bottom Pad Master



UETROC.PcbDoc
Keep Out Layer

.GKO



UETROC.PcbDoc
Drill Drawing For (Bottom Layer)

PCB Fabrication Notes & Stackup

1) Board - 10 Layers (4 Signal, 4Plano, Dimensions 233.39mm x 160.00mm, 2 Sided Silkscreen, 2 Sided Soldermask
2) Trace/width Clearance: 0.127mm (0.25mm)
3) 100 Cu for All Internal Layers, 1500 Cu for Outer Layers
4) Finish Electroless Nickel, Immersion Gold (ENIG)
5) Plating thickness minimum 0.001mm for details
6) All drill hole sizes are specified as finished size.
7) Via hole sizes 0.30mm, to be plugged or tented.
8) Board shall be 100% electrical tested.
9) Soldermask: 15%, 800C
10) 1.6mm +/-10% Total Board Thickness
11) Materials: TOP:FR-4, 1050C Cu, 10350C Cu, 40CTE19 RFR-4 for Leadfree FTGA assembly

PCB STACKUP

Layer #	Thickness	Description	Polarity	Filename	SingleEnded Impedance Requirement	Differential Impedance Requirement
		Solderpaste Top		UETROC.GTP		
		Silkscreen Top		UETROC.GTS		
	0.06mm	Soldermask Top		UETROC.GTS		
1	0.093mm	Top Layer	Positive	UETROC.GTL	0.13mm	0.13mm Width, 0.25mm Gap -> 100ohm +/-10%
	0.1mm	dielectric				
2	0.093mm	Ground 1 Plane	Negative	UETROC.GP1		
	0.1mm	dielectric				
3	0.093mm	Inner Layer 1	Positive	UETROC.G1	0.13mm	0.13mm Width, 0.25mm Gap -> 100ohm +/-10%
	0.1mm					
4	0.093mm	Power Plane 1	Negative	UETROC.GP2		
	0.1mm					
5	0.093mm	Inner Layer 2	Positive	UETROC.G2	0.13mm	0.13mm Width, 0.25mm Gap -> 100ohm +/-10%
	0.1mm					
6	0.093mm	Inner Layer 3	Positive	UETROC.G3	0.13mm	0.13mm Width, 0.25mm Gap -> 100ohm +/-10%
	0.1mm					
7	0.093mm	Power Plane 2	Negative	UETROC.GP3		
	0.1mm					
8	0.093mm	Inner Layer 4	Positive	UETROC.G4	0.13mm	0.13mm Width, 0.25mm Gap -> 100ohm +/-10%
	0.1mm					
9	0.093mm	Ground Plane 2	Negative	UETROC.GP4		
	0.1mm					
10	0.093mm	Bottom Layer	Positive	UETROC.GBL	0.13mm	0.13mm Width, 0.25mm Gap -> 100ohm +/-10%
	0.06mm	Soldermask Bottom		UETROC.GBP		
		Silkscreen Bottom		UETROC.GBS		
		Solderpaste Bottom		UETROC.GBP		

- DRILL FILES
- (1) UETROC.drv - Drill Report File
 - (2) UETROC-plated.txt - NC Drill file for PLATED holes
 - (3) UETROC-notplated.txt - NC Drill file for NON-PLATED holes
 - (4) UETROC.gdt - Drill Drawing-Fab Notes

Symbol	Hit Count	Tool Size	Plated	Hole Type
□	1555	0.254mm (10mil)	PTH	Round
▽	717	0.305mm (12mil)	PTH	Round
○	39	0.33mm (12.992mil)	PTH	Round
×	105	0.475mm (18.7mil)	PTH	Round
☆	4	0.559mm (22mil)	PTH	Round
✱	12	0.7mm (27.559mil)	PTH	Round
○	6	0.9mm (35.433mil)	PTH	Round
◇	320	0.965mm (38mil)	PTH	Round
□	240	1.016mm (40mil)	PTH	Round
⊠	24	1.05mm (41.339mil)	PTH	Round
✱	4	1.55mm (61.024mil)	PTH	Round
⊠	2	1.7mm (66.929mil)	PTH	Round
×	2	2.54mm (100mil)	NPTH	Round
▽	4	2.54mm (100mil)	PTH	Round
◇	5	2.794mm (110mil)	PTH	Round
☆	1	2.794mm (110mil)	NPTH	Round
⊠	1	3.2mm (125.984mil)	NPTH	Round
	3041 Total			

Drilling Details.

UETROC.PcbDoc
Drill Guide For (BottomLayer,TopLayer)

